

TITLE: PACKAGE OUTLINE, 8L TSSOP, 4.40 mm

DOC ID # 21-0175

NEW REV: A

OLD REV: N/A

EFFECTIVE:

TYPE

883

SMD #

PERMANENT

TEMPORARY

EXPIRES:

ORIGINATOR

R DELEON / TONY MAK

EXT: 6451 / 4364

VP NAME: RICH HOOD

OTHER DOC AFFECTED: NO YES LIST: →

MATL. AFFECTED: NO YES →

USE AS IS:

REWORK:

SCRAP:

For Maxfab Lot Traveler Changes ONLY: Affects version number? NO YES IF YES, ECN the Process Revision

For Data Sheet Changes ONLY: Review Data Sheet before printing? NO YES IF YES, initial

DESIGN CHANGES ONLY:

ROOT CAUSE:

CORRECTIVE ACTION:

REASON FOR CHANGE: NEW TSSOP PACKAGE OUTLINE (4.40 mm)

FROM:

TO:

- NEW OUTLINE.

DISTRIBUTION: HQ Maxim North Maxfab South Manufacturing Areas N/A Offshore: AAP

Other: J.MOIST, L.JACKSON, M.RUBENZAHL, S.SUNG, S.SCHROEDER, A.ARREOLA, A.WICHMAN, D.GOLDBAUM, E.EVANS,

COLORADO/AUSTIN/PLANO DESIGN CENTERS.

ORIGINAL APPROVALS ARE ON FILE IN THE _____ DOCUMENT CONTROL OFFICE.

APPROVALS	DATE	APPROVALS	DATE	APPROVALS	DATE
PKG. ENGR.	/ /	AL QUINTERO	/ /		/ /
TONY MAK.	/ /		/ /		/ /
CHAD KEENE	/ /		/ /		/ /

Date ECN submitted into D.C.:

Document Control processor initials:

